

Maximum Ratings @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Drain Source Voltage	V _{DSS}	30	V
Gate-Source Voltage	V _{GSS}	±20	V
Drain Current (Note 4)	I _D	T _A = 25°C	A
		T _A = 70°C	
Drain Current (Note 4)	I _{DM}	20	A
Body-Diode Continuous Current (Note 4)	I _S	2.0	A

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Total Power Dissipation (Note 4)	P _D	1.4	W
Thermal Resistance, Junction to Ambient @T _A = 25°C (Note 4)	R _{θJA}	90	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

Electrical Characteristics @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 5)						
Drain-Source Breakdown Voltage	BV _{DSS}	30	—	—	V	V _{GS} = 0V, I _D = 250μA
Zero Gate Voltage Drain Current	I _{DSS}	—	—	800	nA	V _{DS} = 30V, V _{GS} = 0V
Gate-Body Leakage	I _{GSS}	—	—	±80 ±800	nA	V _{GS} = ±20V, V _{DS} = 0V V _{GS} = ±25V, V _{DS} = 0V
ON CHARACTERISTICS (Note 5)						
Gate Threshold Voltage	V _{GS(th)}	1.3	1.9	2.2	V	V _{DS} = V _{GS} , I _D = 250μA
Static Drain-Source On-Resistance	R _{DS(ON)}	—	47 92	57 112	mΩ	V _{GS} = 10V, I _D = 5.8A V _{GS} = 4.5V, I _D = 4.2A
Forward Transconductance	Y _{fs}	—	4.7	—	S	V _{DS} = 5V, I _D = 4.2A
Source-Drain Diode Forward Voltage	V _{SD}	—	0.78	1.1	V	V _{GS} = 0V, I _S = 2.0A
DYNAMIC CHARACTERISTICS						
Input Capacitance	C _{iss}	—	268	—	pF	V _{DS} = 5V, V _{GS} = 0V f = 1.0MHz
Output Capacitance	C _{oss}	—	73	—	pF	
Reverse Transfer Capacitance	C _{rss}	—	50	—	pF	

Notes: 2. Device mounted on FR-4 PCB. t ≤ 5 sec.
3. Short duration pulse test used to minimize self-heating effect.